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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HA12211NT

Audio Signal Processor for Cassette Deck (Deck 1 Chip)



ADE-207-223A (Z)

2nd. Edition
June 1997

Description

HA12211NT is silicon monolithic bipolar IC providing REC equalizer system, PB equalizer system and each electronic control switch in one chip.

Functions

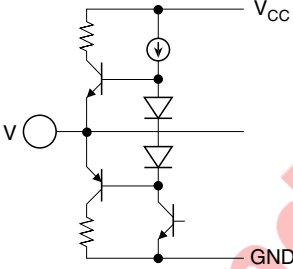
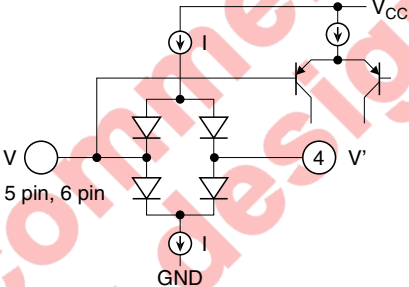
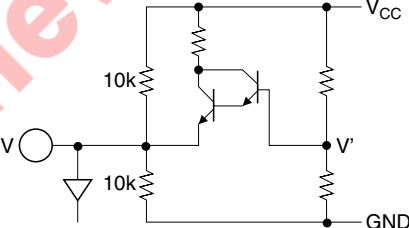
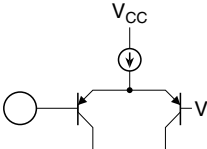
- PB equalizer × 2 channel
- REC equalizer × 2 channel
- Each electronical control switch to change equalizer characteristics
- REC mute
- REC head return switch

Features

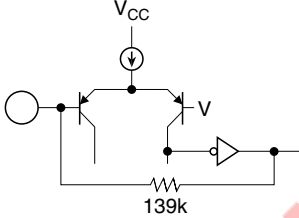
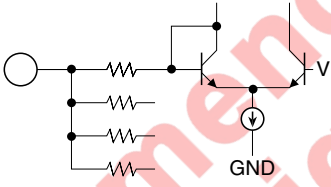
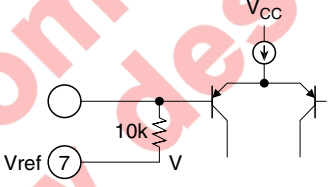
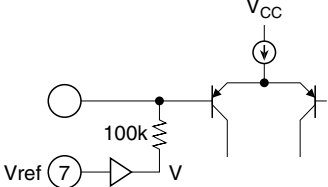
- REC equalizer is very small number of external parts.(4 types of frequency characteristics built-in)
- PB equalizer built-in. (A/B input changing system, 4 types of frequency characteristics)
- Independent PB sensitivity for A deck, B deck.
- Normal-speed/high-speed, normal tape/chrome tape switching built-in.
- Controllable from direct micro-computer output.
- Available to reduce substrate-area because of high integration and small external parts.

HA12211NT

Pin Description, Equivalent Circuit ($V_{cc} = 10.5V$, $V_{ref} = 5.25V$, $T_a = 25^{\circ}C$, No signal, The value in the table show typical value.)

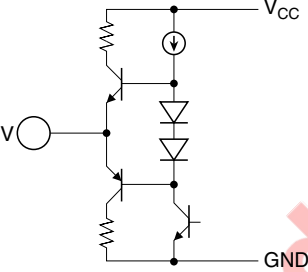
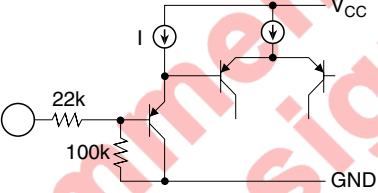
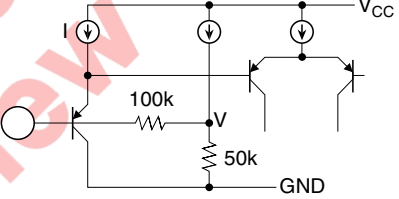
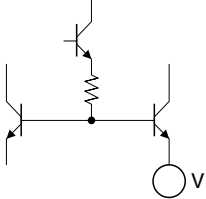
Pin No.	Pin Name	Note	Equivalent Circuit	Pin Description
1	V_{cc}	$V = V_{cc}$		V_{cc} Pin
2	RECOUT (L)	$V = V_{ref}$		REC-EQ output
3	RECOUT (R)			
4	REC-RETURN	$V = V_{ref}$ $V' = V_{ref}$		REC Return
5	PB-IN B (L)			PB B Deck input
6	PB-IN B (R)			
7	VREF	$V = V_{ref}$ $V' = V_{cc} / 2$		Reference
8	PB-IN A(L)	$V = V_{ref}$		PB A Deck input
9	PB-IN A(R)			

Pin Description, Equivalent Circuit ($V_{CC} = 10.5V$, $V_{ref} = 5.25V$, $T_a = 25^{\circ}C$, No signal, The value in the table show typical value.) (cont)

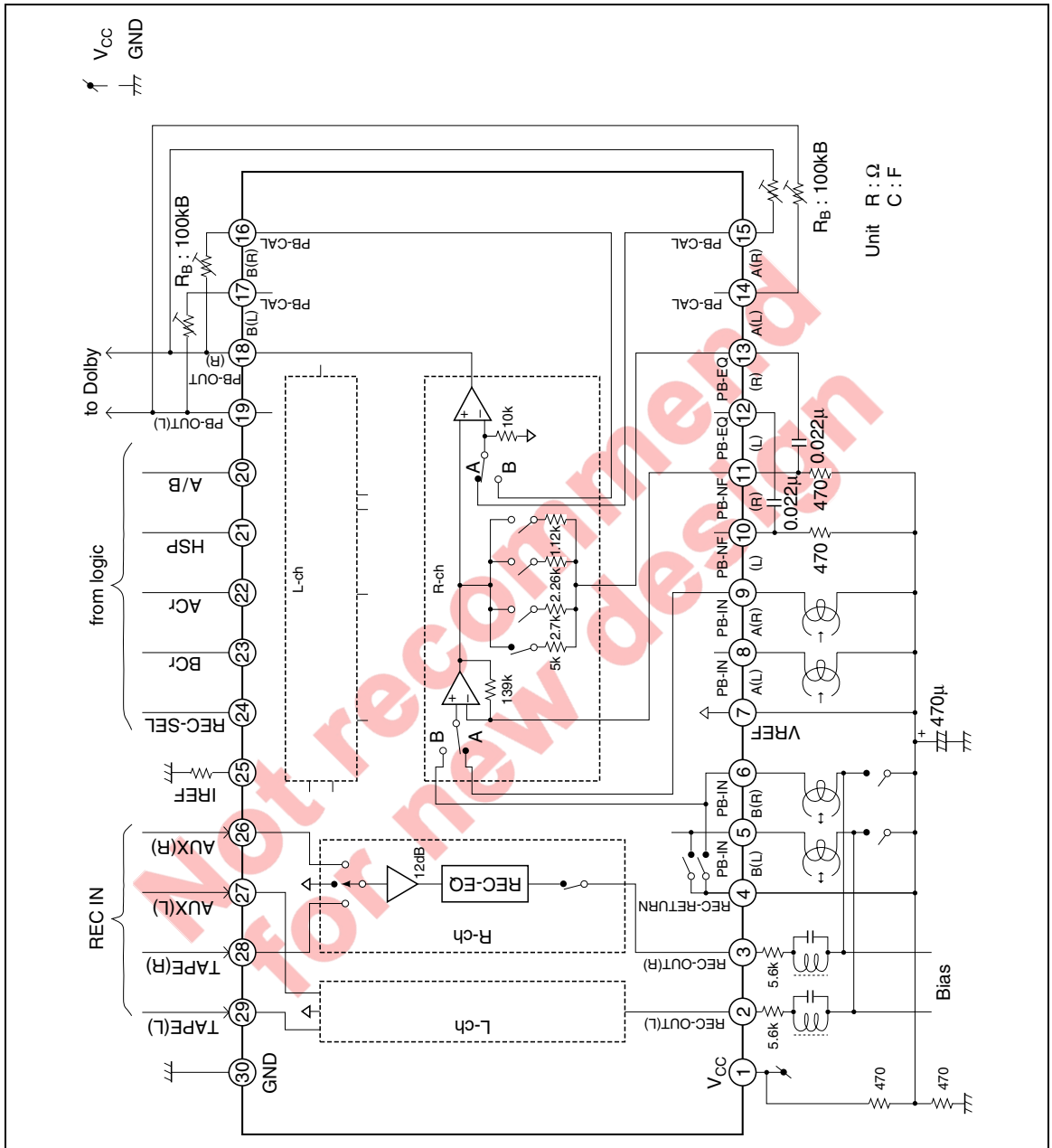
Pin No.	Pin Name	Note	Equivalent Circuit	Pin Description
10	PB-NF (L)	$V = V_{ref}$		PB EQ Feed back
11	PB-NF (R)			
12	PB-EQ (L)	$V = V_{ref}$		NAB Output
13	PB-EQ (R)			
14	PB-Cal A(L)	$V = V_{ref}$		Feed back input for gain adjustment
15	PB-Cal A(R)			
16	PB-Cal B(R)			
17	PB-Cal B(L)			
26	AUX (R)	$V = V_{ref}$		REC-EQ input
27	AUX (L)			
28	TAPE (R)			
29	TAPE (L)			

HA12211NT

Pin Description, Equivalent Circuit ($V_{cc} = 10.5V$, $V_{ref} = 5.25V$, $T_a = 25^{\circ}C$, No signal, The value in the table show typical value.) (cont)

Pin No.	Pin Name	Note	Equivalent Circuit	Pin Description
18	PBOUT (R)	$V = V_{ref}$		PB output
19	PBOUT (L)			
20	A/B	$I = 20\mu A$		Mode control input
21	HSP			
22	Acr			
23	Bcr			
24	REC-SEL	$I = 20\mu A$ $V = 2.5V$		Mode control input
25	IREF	$V = 1.2V$		Equalizer reference current input
30	GND			GND Pin

Block Diagram



HA12211NT

Parallel Data Format

Pin No.	Pin Name	L	M	H
22	A CrO2	*1, *3	—	*1
23	B CrO2	*1, *2, *3	—	*1, *2
21	HSP	Normal speed *3	—	Hi speed
20	A/B	Ain active *1, *3	—	Bin active *1
		Return SW ON *3	—	Return SW OFF
		REC OUT active *3	—	REC OUT Hiz
24	REC IN SEL	TAPE	MUTE *3	AUX

Note: 1. PB-EQ LOGIC

		HSP			
		L		H	
		A/B			
A CrO2	B CrO2	L	H	L	H
L	L	120μ	120μ	60μ	60μ
L	H	120μ	70μ	60μ	35μ
H	L	70μ	120μ	35μ	60μ
H	H	70μ	70μ	35μ	35μ

2. REC-EQ LOGIC

		HSP	
B CrO2		L	H
L		Normal speed TAPE I	High speed TAPE I
H		Normal speed TAPE II	High speed TAPE II

3. Unforced pin state

Functional Description

Power Supply Range

This IC is designed to operate on single supply, shown by table 1.

Table 1 Spply Voltage

Item	Power Supply Range
Single Supply	9.5V to 15.0V

Reference Voltage

So little is the current drivability of AC reference (Vref) that the Vref voltage may be altered by A/B switching of PB-EQ.

Provided it causes you anxiety, please use the constant 1/2 V_{cc} voltage circuit, for example, figure 1.

In addition, this IC has a capacitor charger for Vref pin.

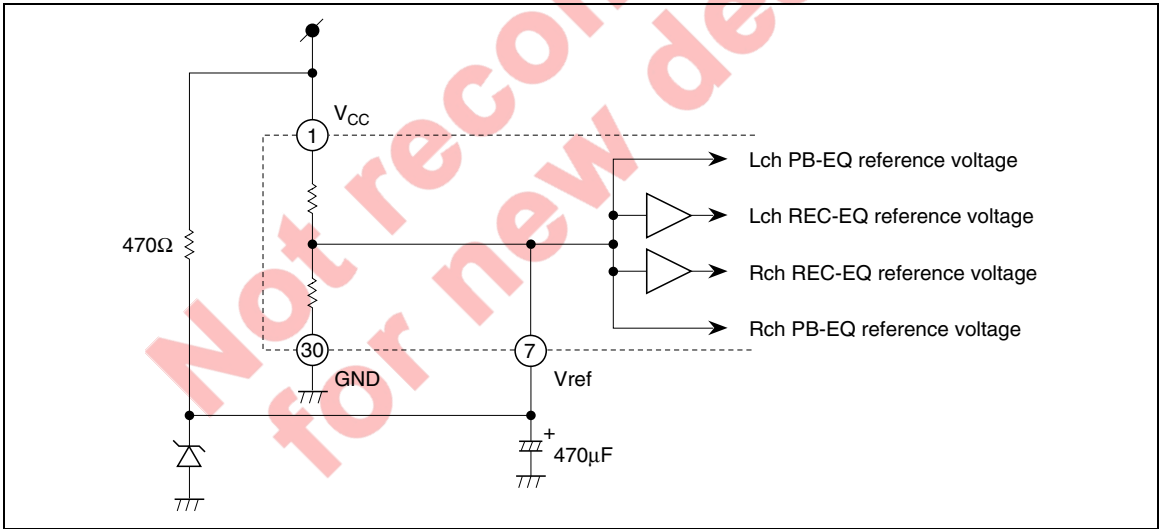


Figure 1 Reference Voltage Circuit

Level Diagram

It is the target that total play back output level is adjusted to 300mV; Dolby level, which the PB system gain in all is included of external amplifier's (Dolby IC etc.) as follows figure 3. Though A head adjustment is independent of B, select the value of R9, R18 adequately.

Regarding REC-EQ adjust the gain in front of input to this IC.

The level diagram at 1kHz is shown by figure 4.

- Note:
1. R1 needs the value more than 1kHz.
 2. Depending on the employed REC/PB head and test tape characteristics, there is rare case that the REC-EQ frequency characteristics of this IC can not be matched to the required characteristics because of built-in resistors which determined the REC-EQ parameters in this case, please inquire the responsible agent because of the adjustment of built-in resistors is necessary.

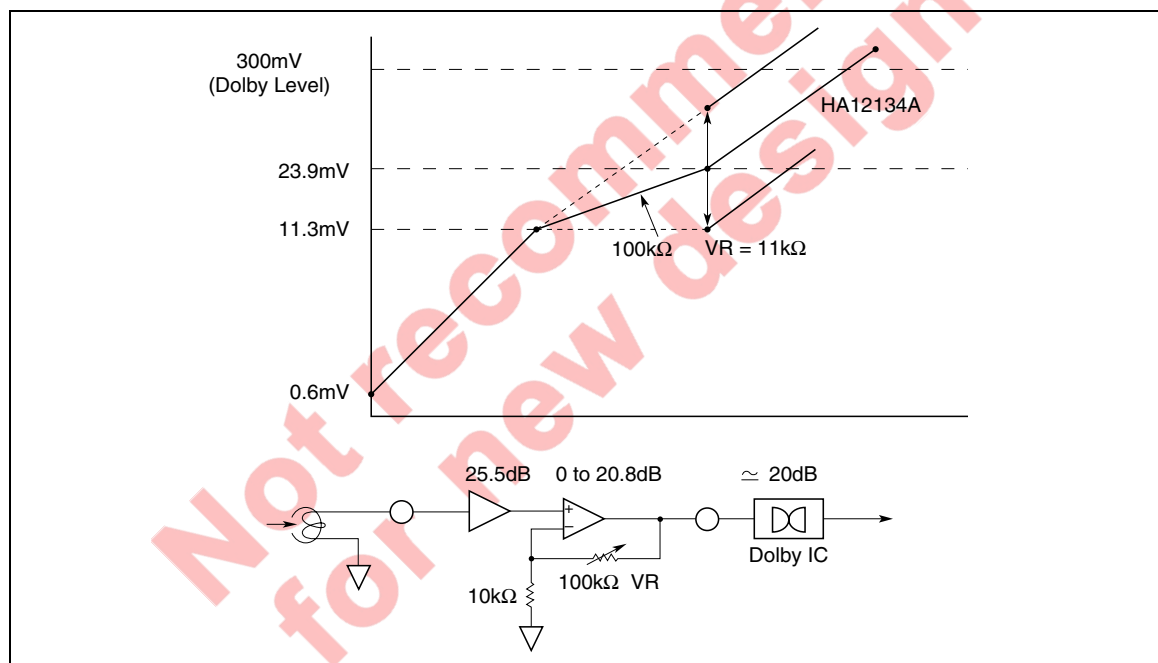


Figure 3 PB Level Diagram (Normal Speed, Normal Tape, 1kHz)

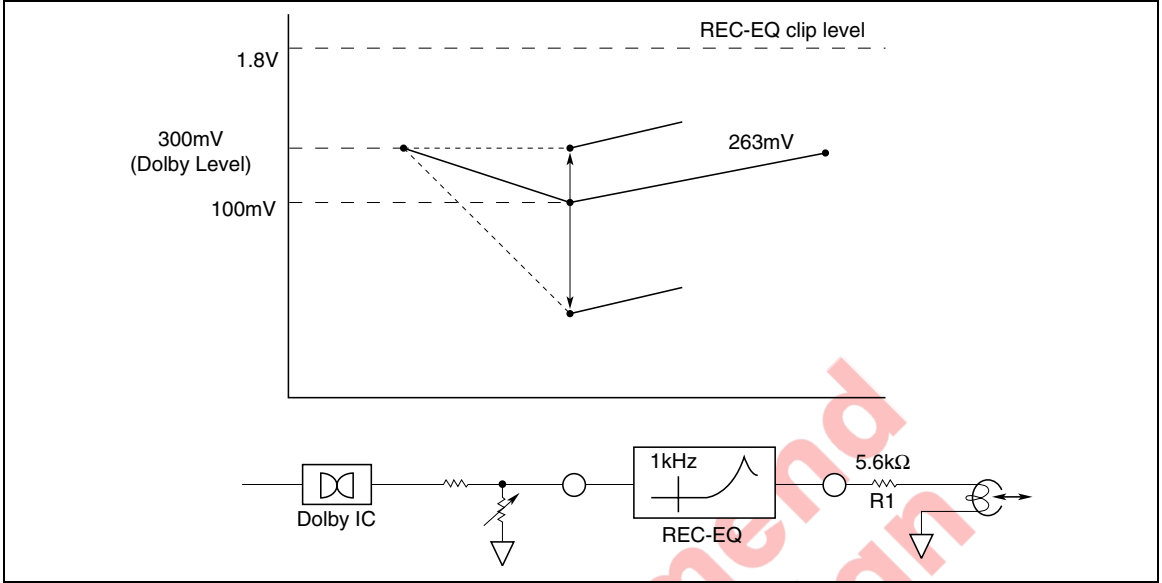


Figure 4 REC Level Diagram (Normal Speed, Normal Tape, 1kHz)

Absolute Maximum Rating (Ta = 25°C)

Item	Symbol	Rating	Unit	Note
Max supply voltage	V _{cc} max	16	V	
Power dissipation	P _d	500	mW	Ta ≤ 75°C
Operating temperature	Topr	−40 to +75	°C	
Storage temperature	Tstg	−55 to +125	°C	
Operating voltage	Vopr	9.5 to 15	V	

Not recommend
for new design

Electrical Characteristics (Ta = 25°C, V_{cc} = 10.5V, V_{ref} = 5.25V, PB-EQ standard DC gain 55.9dB (R9, R10, R18, R19 = 11.0kΩ))

Test Condition													Application				
IC Condition													Input		Terminal Output		
Item	Symbol	Min	Type	Max	Unit	A/B	HSP	A CrO2 B CrO2	REC	f _{in}	V _{in}	Other	R	L	R	L	COM
Quiescent current	I _Q	16.0	22.8	32.0	mA	A	Norm	TYPE I TYPE I	Mute	—	—	No signal	—	—	—	—	1
Logical threshold	V _{IL} 1	-0.2	—	2.5	V	—	—	—	—	—	—	—	—	—	—	—	20 to 23
	V _{IL} 2	-0.2	—	1.0	V	—	—	—	—	—	—	—	—	—	—	—	24
	V _{IM}	2.0	—	3.0	V	—	—	—	—	—	—	—	—	—	—	—	24
	V _{IH}	4.0	—	V _{CC}	V	—	—	—	—	—	—	—	—	—	—	—	20 to 24
PB-REC Crosstalk	CT PB/REC(1)	50	60	—	dB	A/B	Norm	TYPE I TYPE I	Tape/ AUX	1k	*1	—	27/ 29	26/ 28	18	19	—
	CT PB/REC(2)	60	70	—	dB	A	Norm	TYPE I TYPE I	Tape/ AUX	1k	*1	—	9	8	3	2	—
PB-EQ Gain	G _V PB (1)	29.0	32.0	35.0	dB	A/B	Norm	TYPE I TYPE I	Tape	1k	0.6	—	9/6	8/5	18	19	—
	G _V PB (2)	25.0	28.0	31.0	dB	A/B	Norm	TYPE I TYPE I	Tape	10k	0.6	—	9/6	8/5	18	19	—
	G _V PB (3)	20.8	23.8	26.8	dB	A/B	Norm	TYPE II TYPE II	Tape	10k	0.6	—	9/6	8/5	18	19	—
	G _V PB (4)	19.4	22.4	25.4	dB	A/B	High	TYPE I TYPE I	Tape	20k	0.6	—	9/6	8/5	18	19	—
	G _V PB (5)	14.8	17.8	20.8	dB	A/B	High	TYPE II TYPE II	Tape	20k	0.6	—	9/6	8/5	18	19	—
	PB-EQ Maximum output	Vomax PB	0.3	2.0	—	Vrms	A/B	Norm	TYPE I TYPE I	Tape	1k	—	THD=1%*2	9/6	8/5	18	19
PB-EQ THD	THD PB	—	0.1	0.5	%	A/B	Norm	TYPE I TYPE I	Tape	1k	0.6	—	9/6	8/5	18	19	—
PB-EQ Noise voltage	V _N PB	—	38	70	μVrms	A/B	Norm	TYPE I TYPE I	Tape	—	—	Rg=820Ω, DIN-AUDIO	9/6	8/5	18	19	—
PB-EQ Channel separation	CT R/L (1)	50	60	—	dB	A/B	Norm	TYPE I TYPE I	Tape	1k	*1	—	8/5	9/6	18	19	—
	CT A/B	60	70	—	dB	A	Norm	TYPE I TYPE I	Tape	1k	*1	—	11	10	18	19	—
PB-EQ Crosstalk						B							9	8			

Note: 1. Large level without clipping

2. $V_{CC} = 9.5V$, $V_{ref} = 4.75V$, R9, R10, R18, R19 = $56k\Omega$

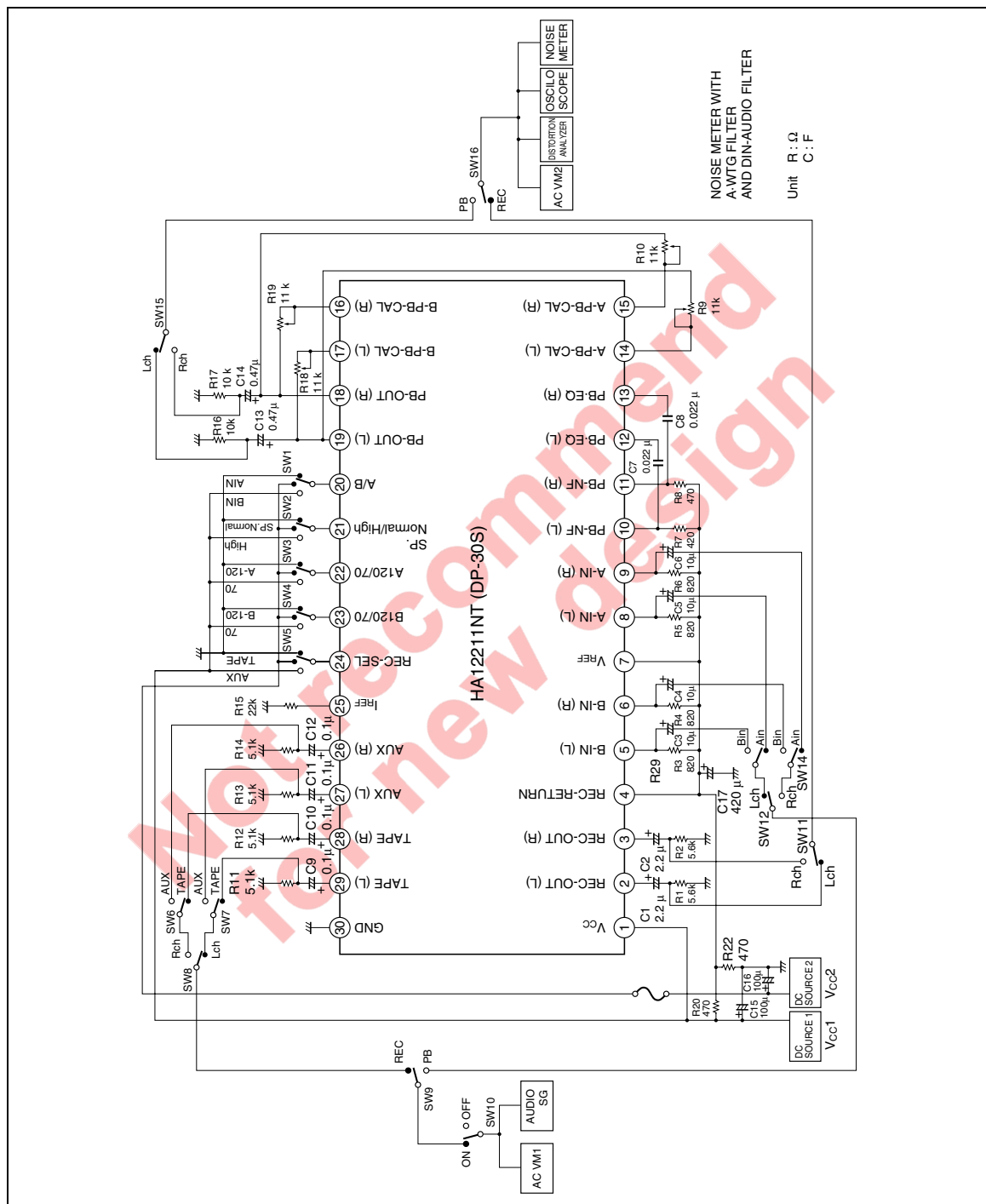
Electrical Characteristics ($T_a = 25^\circ\text{C}$, $V_{cc} = 10.5\text{V}$, $V_{ref} = 5.25\text{V}$, EQIN standard level = $100\text{mV} = 0\text{dB}$) (cont)

Item	Symbol	Min	Typ	Max	Unit	Test Condition		A CrO2 B CrO2 IN SEL	REC fin (Hz)	V _{in} (mVrms)	Application Terminal			
						IC Condition					Input	Output		
REC-EQ Frequency response Normal speed TYPE I	G _V REC-NN 1	6.7	8.2	9.7	dB	A	Norm	TYPE I	TYPE I Tape/ AUX	1k	10	26/ 28	27/ 29	3 2
	G _V REC-NN 2	9.3	11.3	13.3	dB	A	Norm	TYPE I	TYPE I Tape/ AUX	5k	10	26/ 28	27/ 29	3 2
	G _V REC-NN 3	17.3	20.3	23.3	dB	A	Norm	TYPE I	TYPE I Tape/ AUX	10k	10	26/ 28	27/ 29	3 2
REC-EQ Frequency response Normal speed TYPE II	G _V REC-NC 1	9.8	11.3	12.8	dB	A	Norm	TYPE I	TYPE II Tape/ AUX	1k	10	26/ 28	27/ 29	3 2
	G _V REC-NC 2	14.2	16.2	18.2	dB	A	Norm	TYPE I	TYPE II Tape/ AUX	5k	10	26/ 28	27/ 29	3 2
	G _V REC-NC 3	20.5	23.5	26.5	dB	A	Norm	TYPE I	TYPE II Tape/ AUX	10k	10	26/ 28	27/ 29	3 2
REC-EQ Frequency response High speed TYPE I	G _V REC-HN 1	7.0	8.5	10.0	dB	A	High	TYPE I	TYPE I Tape/ AUX	2k	10	26/ 28	27/ 29	3 2
	G _V REC-HN 2	10.9	12.9	14.9	dB	A	High	TYPE I	TYPE I Tape/ AUX	10k	10	26/ 28	27/ 29	3 2
	G _V REC-HN 3	18.7	21.7	24.7	dB	A	High	TYPE I	TYPE I Tape/ AUX	20k	10	26/ 28	27/ 29	3 2
REC-EQ Frequency response High speed TYPE II	G _V REC-HC 1	11.0	12.5	14.0	dB	A	High	TYPE I	TYPE II Tape/ AUX	2k	10	26/ 28	27/ 29	3 2
	G _V REC-HC 2	16.2	18.2	20.2	dB	A	High	TYPE I	TYPE II Tape/ AUX	10k	10	26/ 28	27/ 29	3 2
	G _V REC-HC 3	23.7	26.7	29.7	dB	A	High	TYPE I	TYPE II Tape/ AUX	20k	10	26/ 28	27/ 29	3 2
REC-EQ Channel separation	CT R/L (2)	50	60	—	dB	A	Norm	TYPE I	TYPE I Tape/ AUX	1k	*1	26/ 28	27/ 29	3 2
REC-EQ Crosstalk	CT Tape/AUX	50	60	—	dB	A	Norm	TYPE I	TYPE I Tape/ AUX	1k	*1	26/ 28	27/ 29	3 2
REC-EQ Attenuation	R-MUTE ATT	70	80	—	dB	A	Norm	TYPE I	TYPE I Mute	1k	*1	26/ 28	27/ 29	3 2
REC-EQ Maximum output	Vomax REC	1.2	1.8	—	Vrms	A	Norm	TYPE I	TYPE I Tape/ AUX	1k	—	26/ 28	27/ 29	3 2
REC-EQ THD	THD REC	—	0.35	0.7	%	A	Norm	TYPE I	TYPE I Tape/ AUX	1k	100	26/ 28	27/ 29	3 2
REC-EQ S/N	S/N REC	52	56	—	dB	A	Norm	TYPE I	TYPE I Tape/ AUX	—	—	26/ 28	27/ 29	3 2

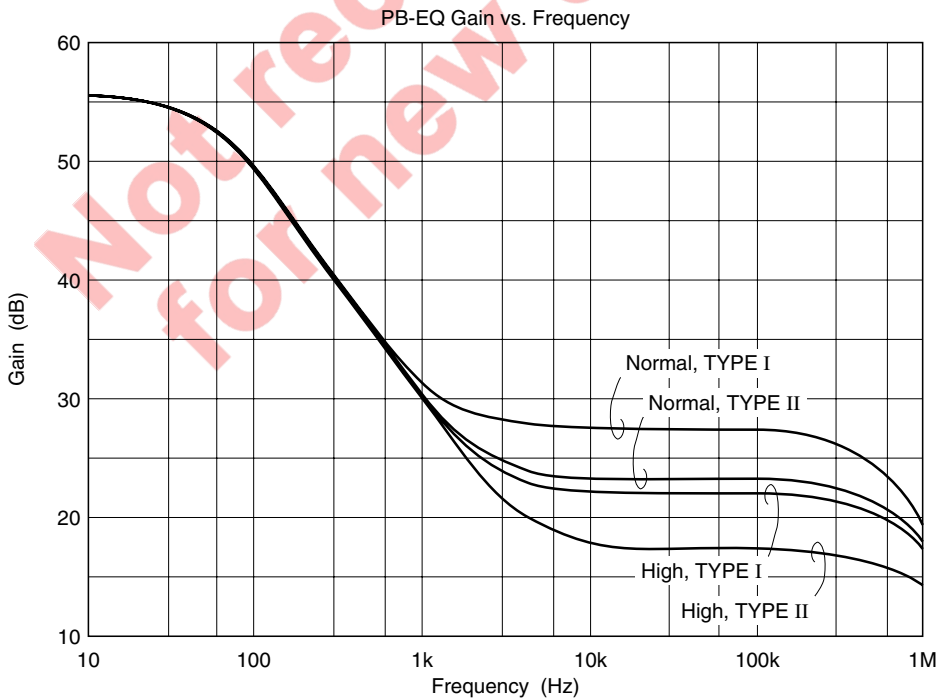
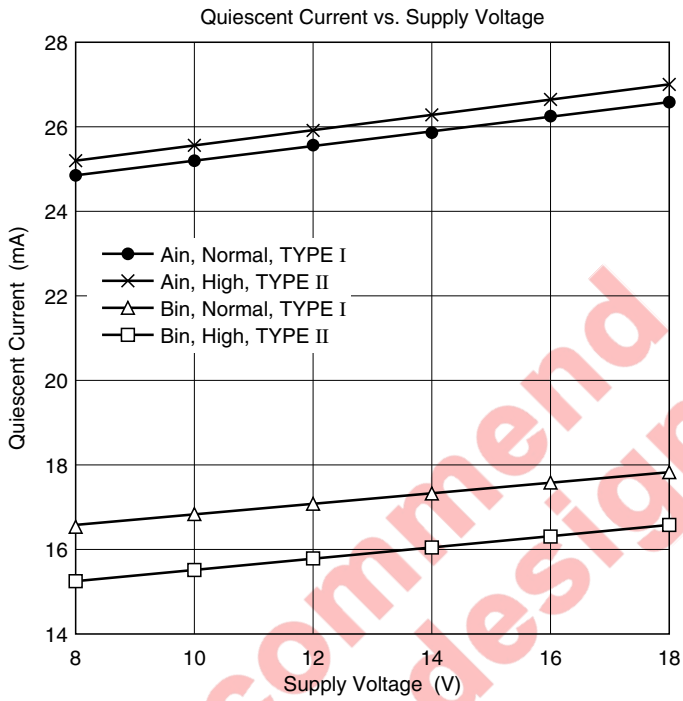
Note: 1. Large level without clipping
2. $V_{cc} = 9.5\text{V}$, $V_{ref} = 4.75\text{V}$

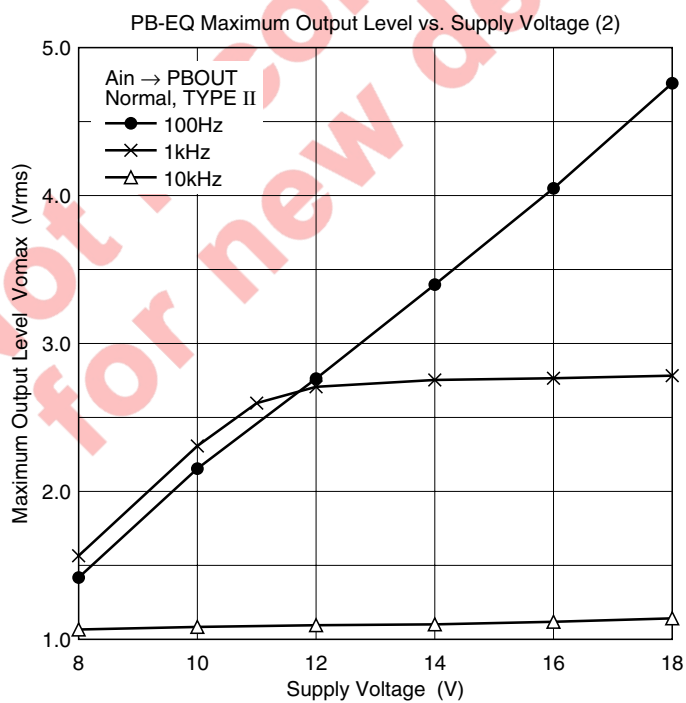
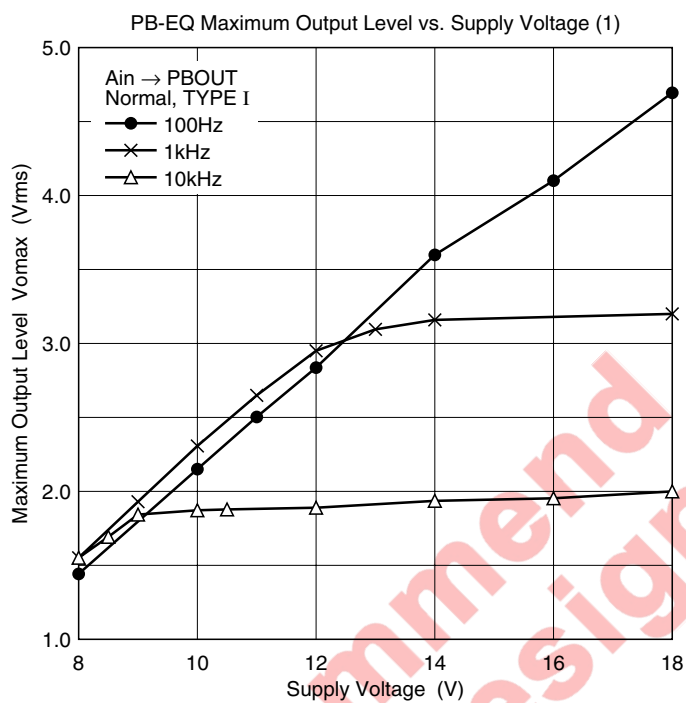
HA12211NT

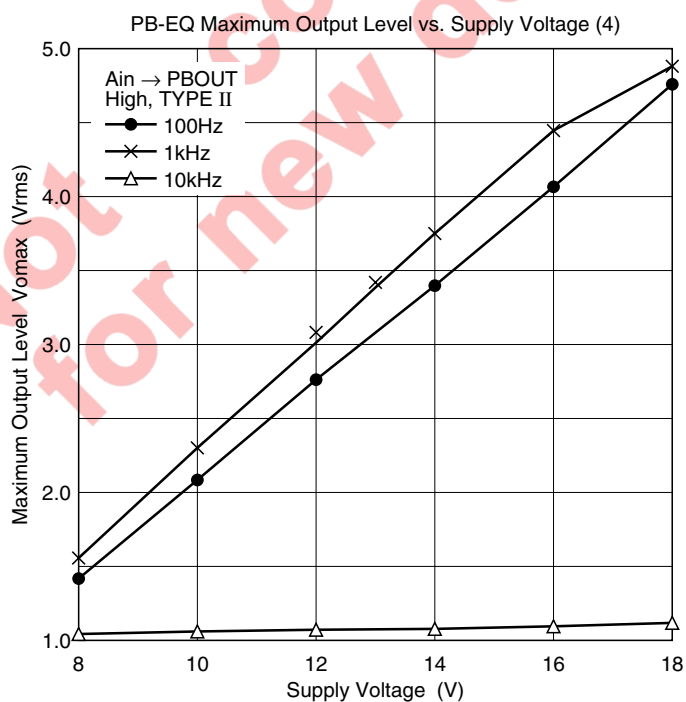
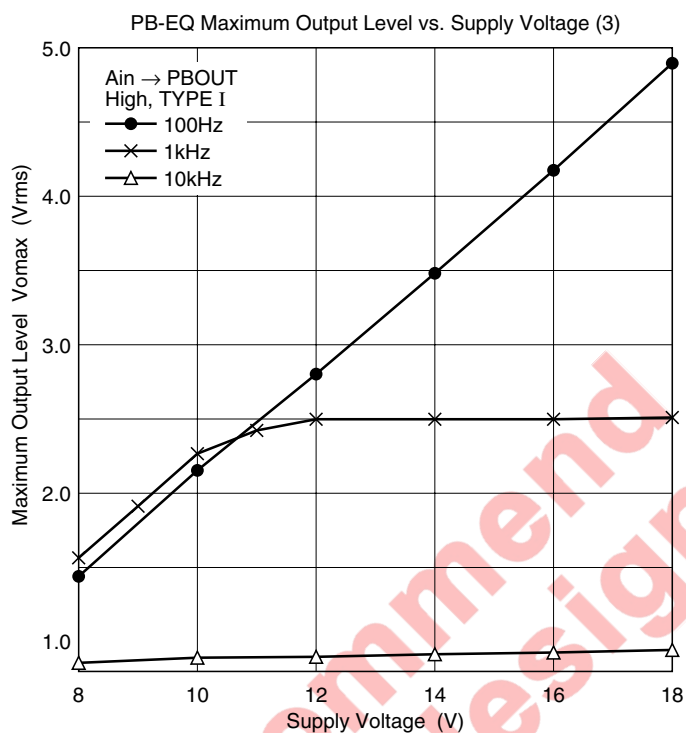
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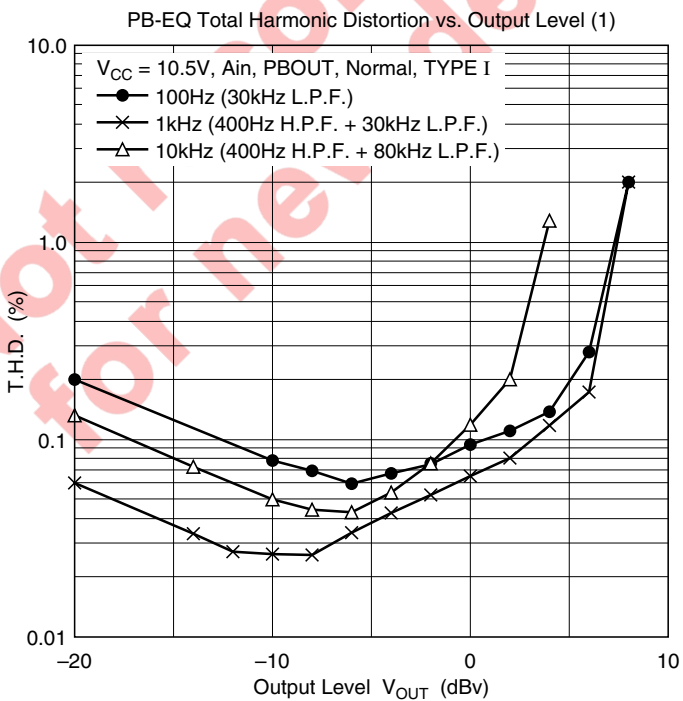
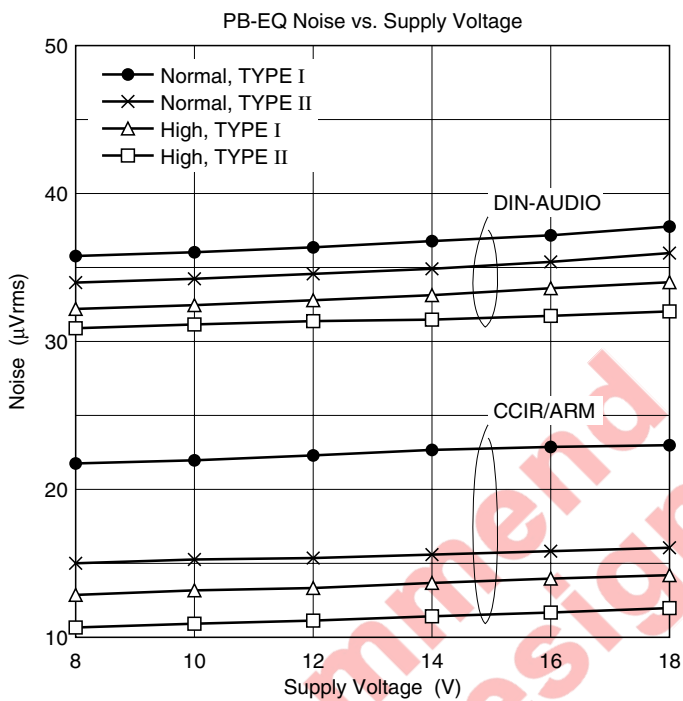


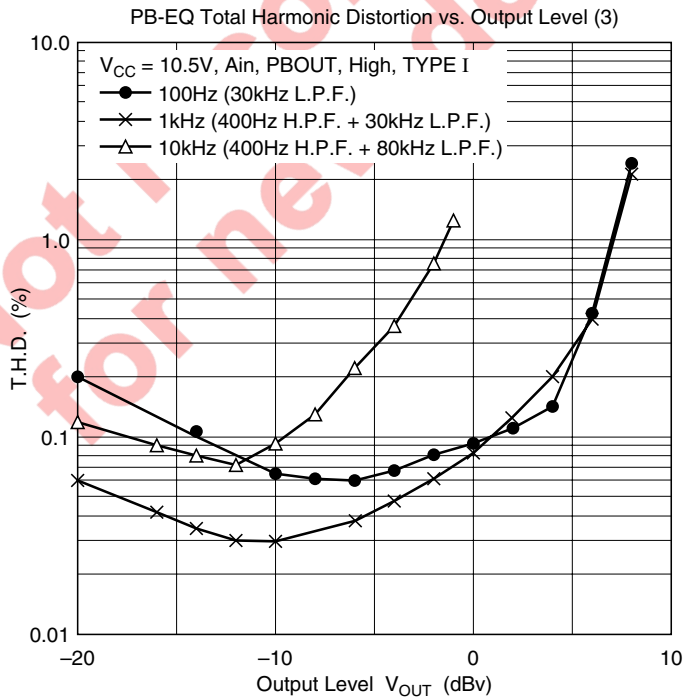
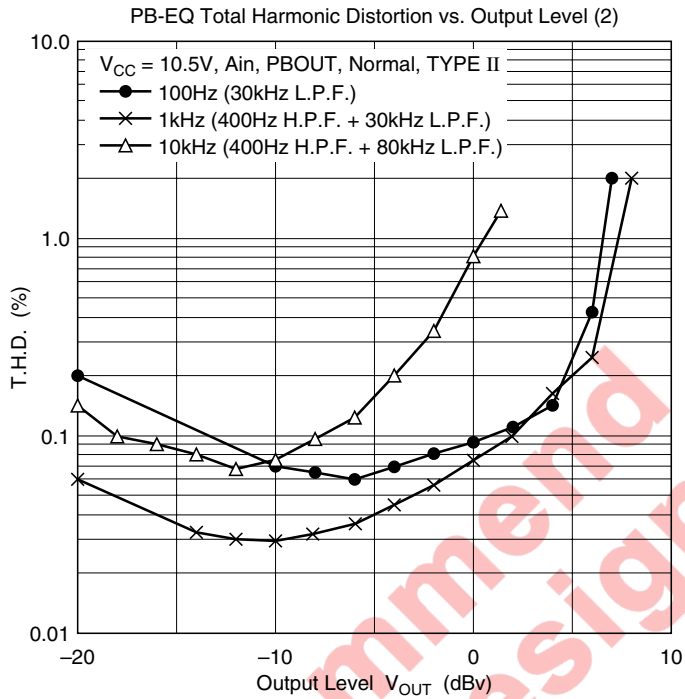
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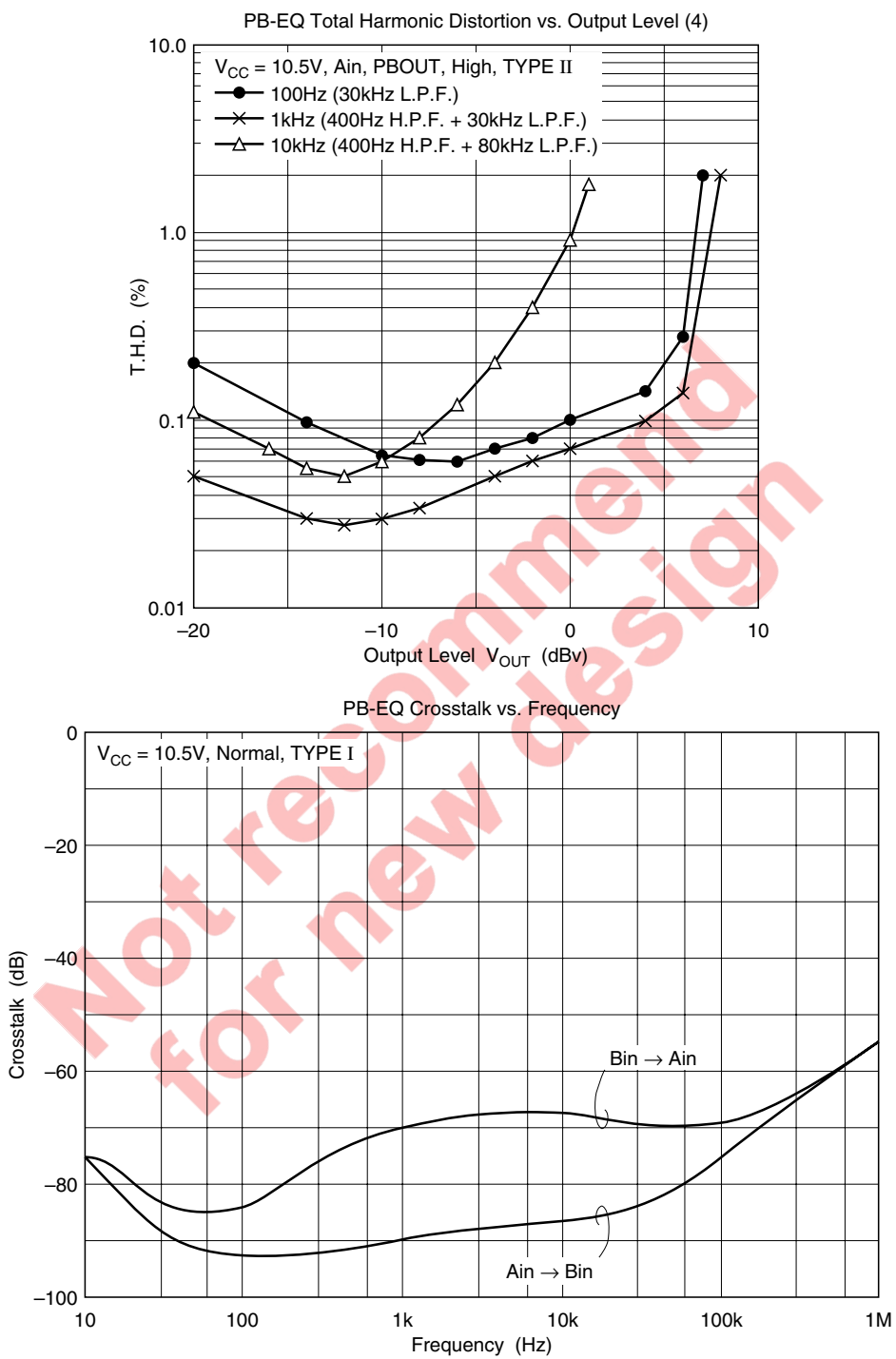


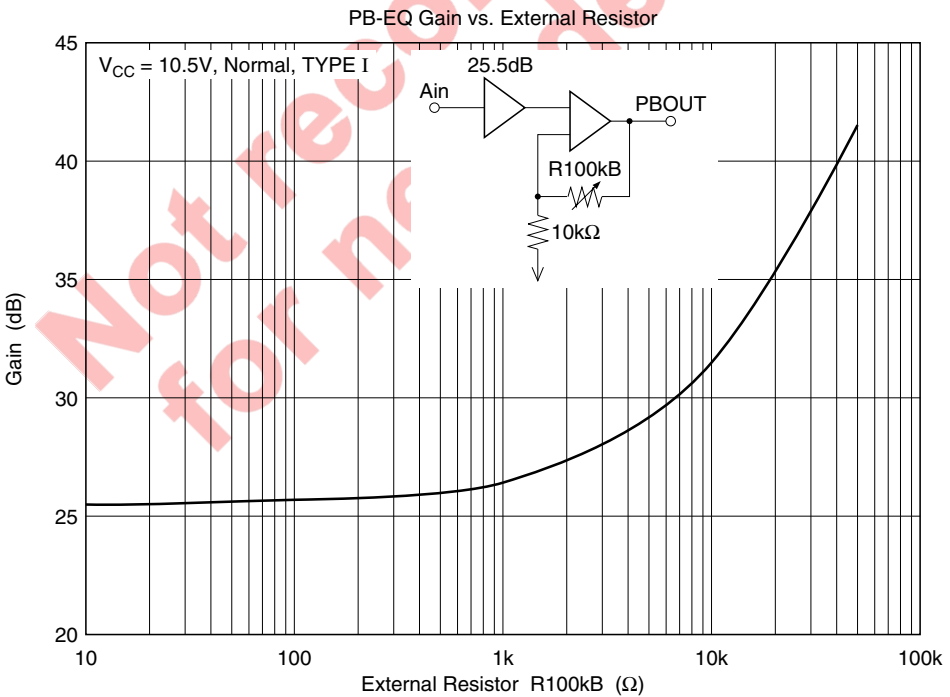
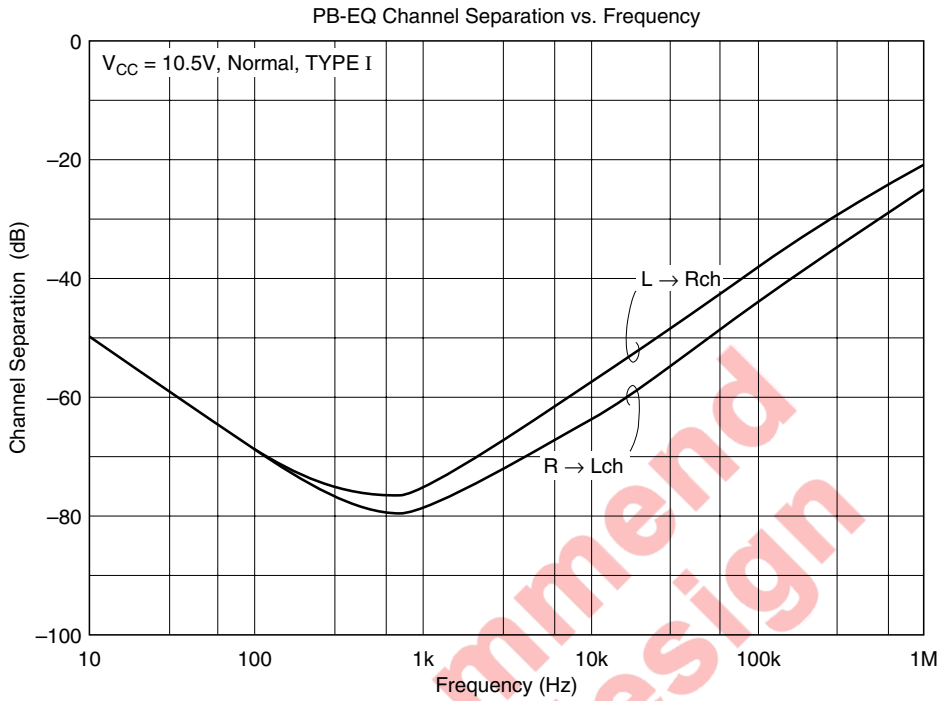


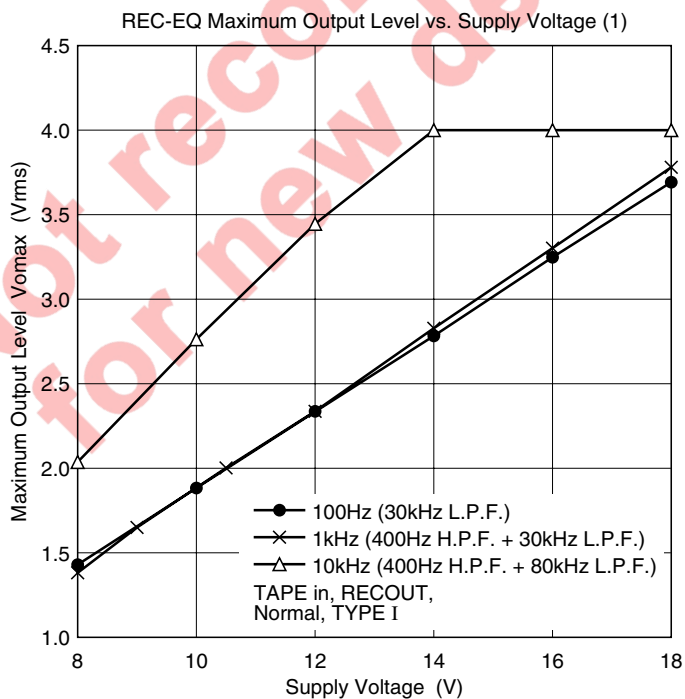
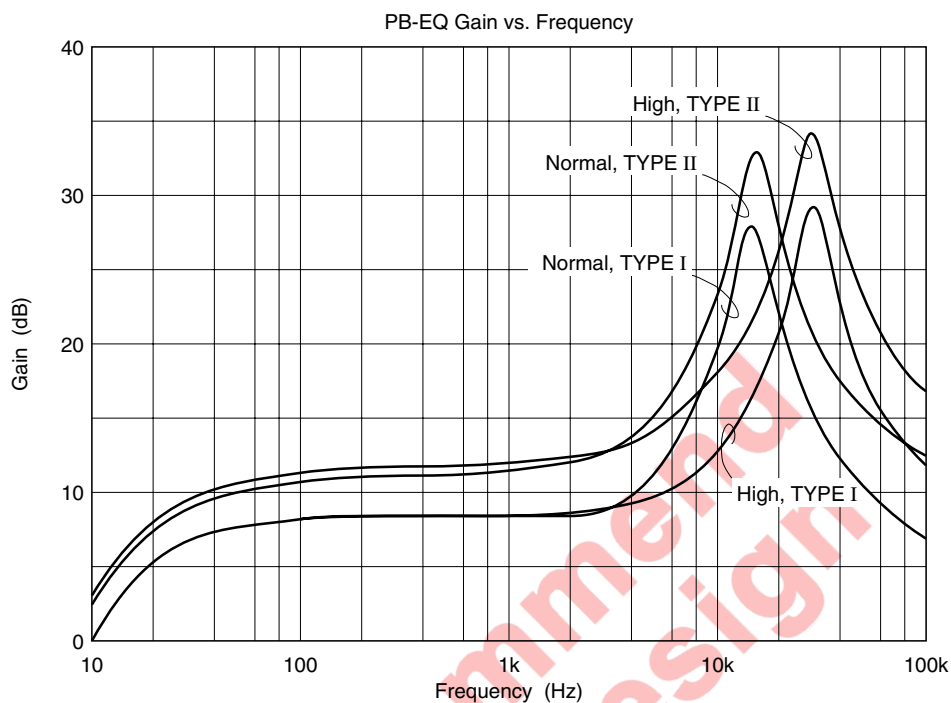


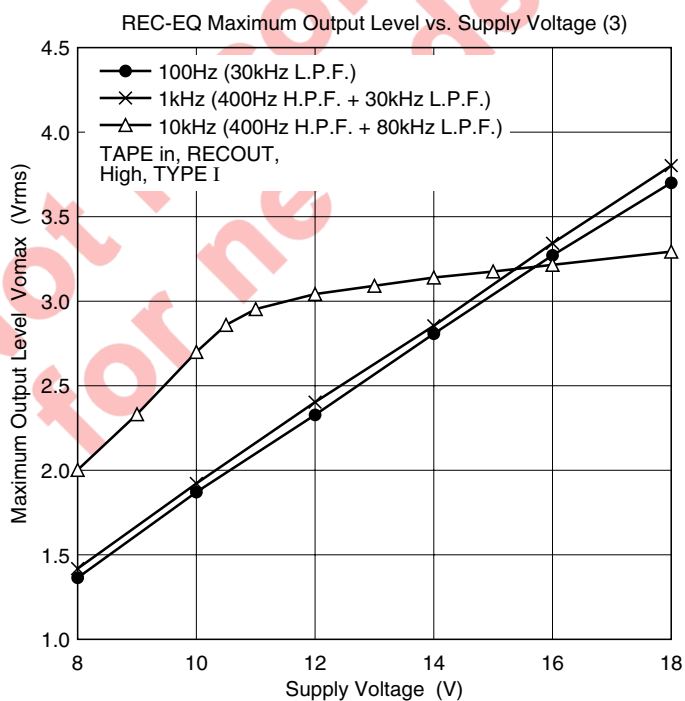
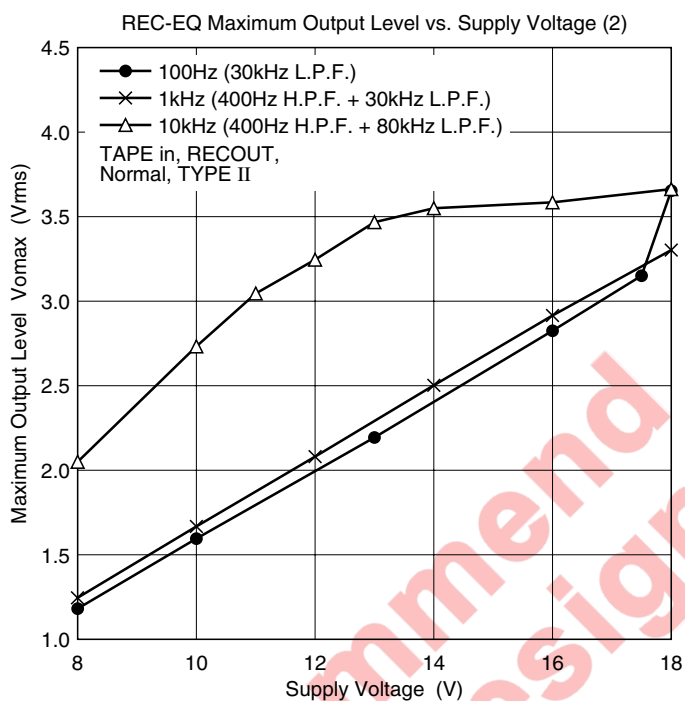


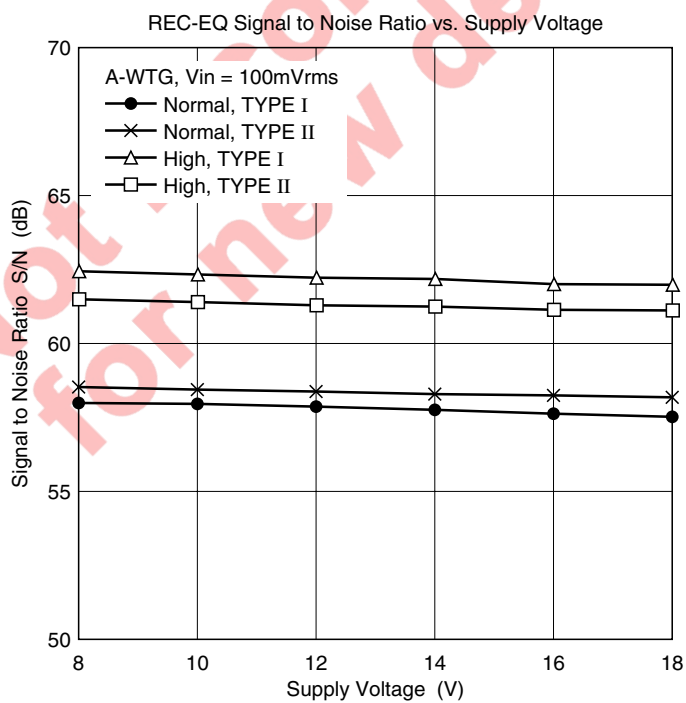
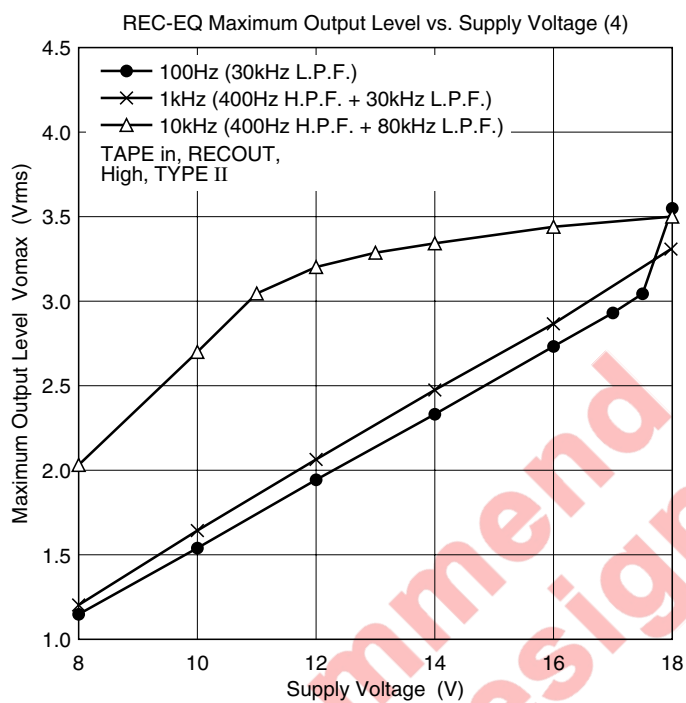


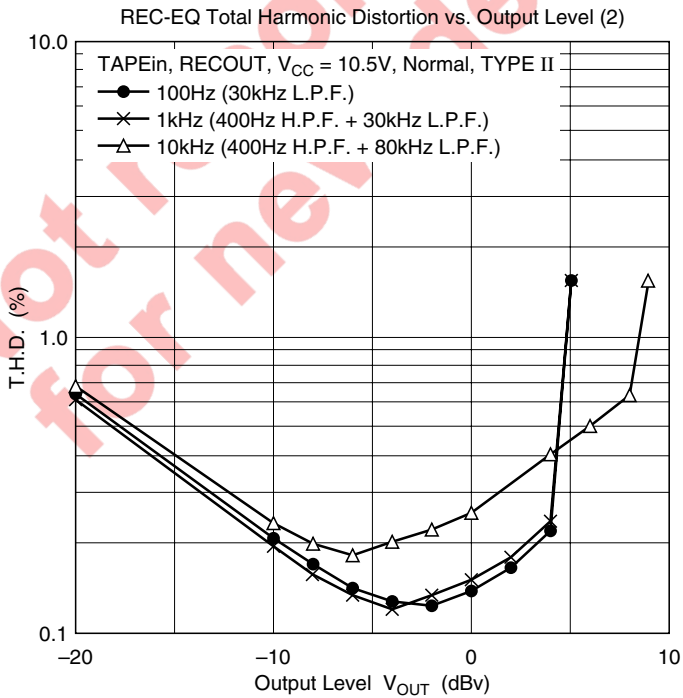
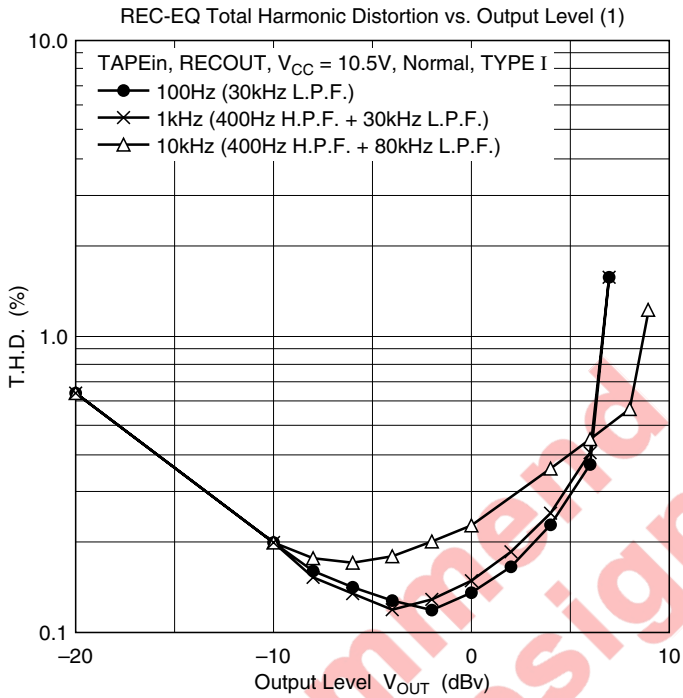


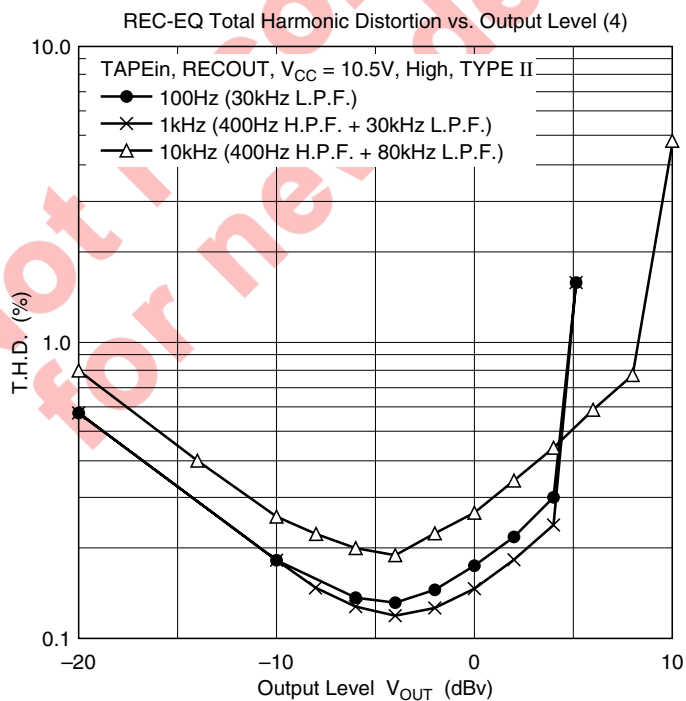
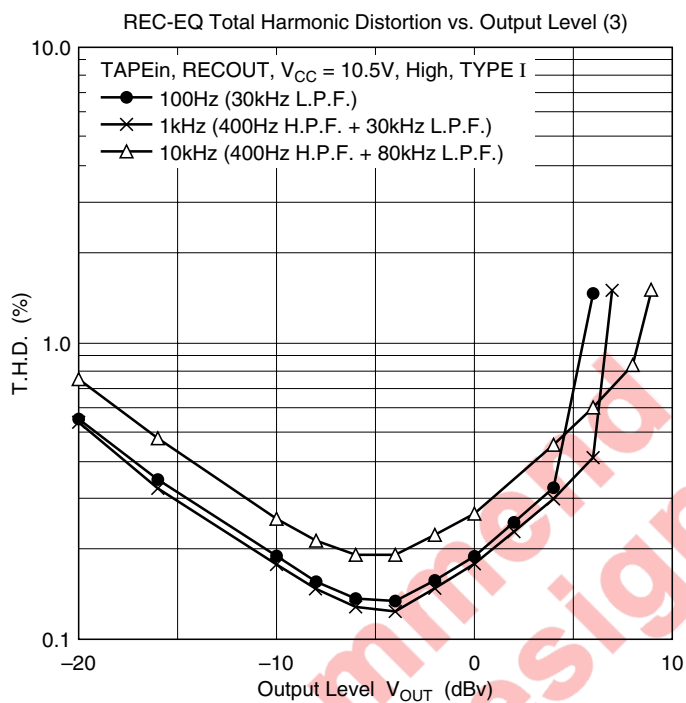


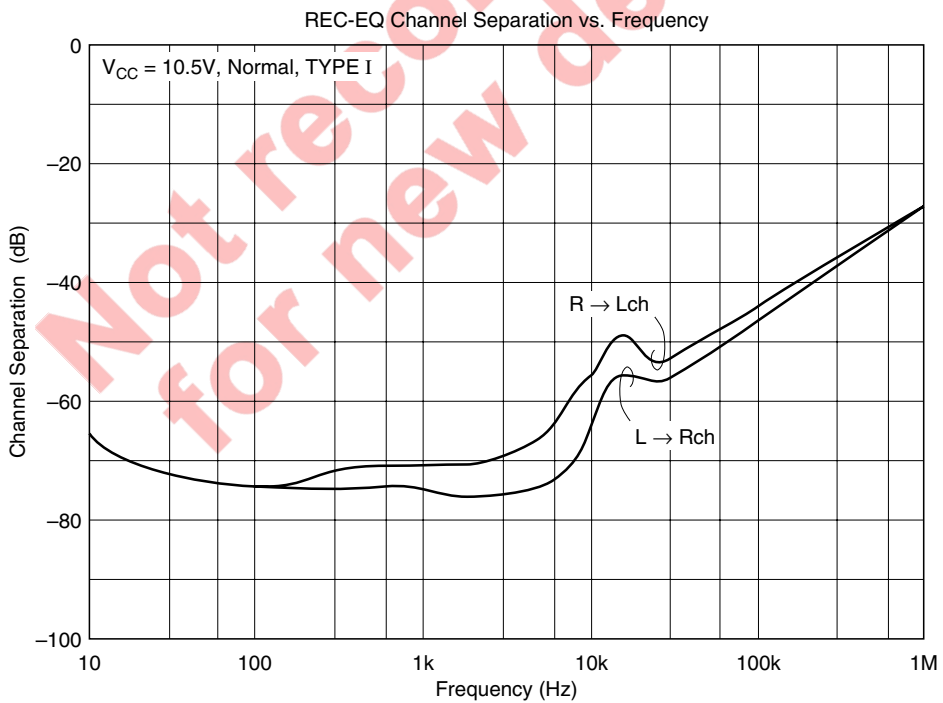
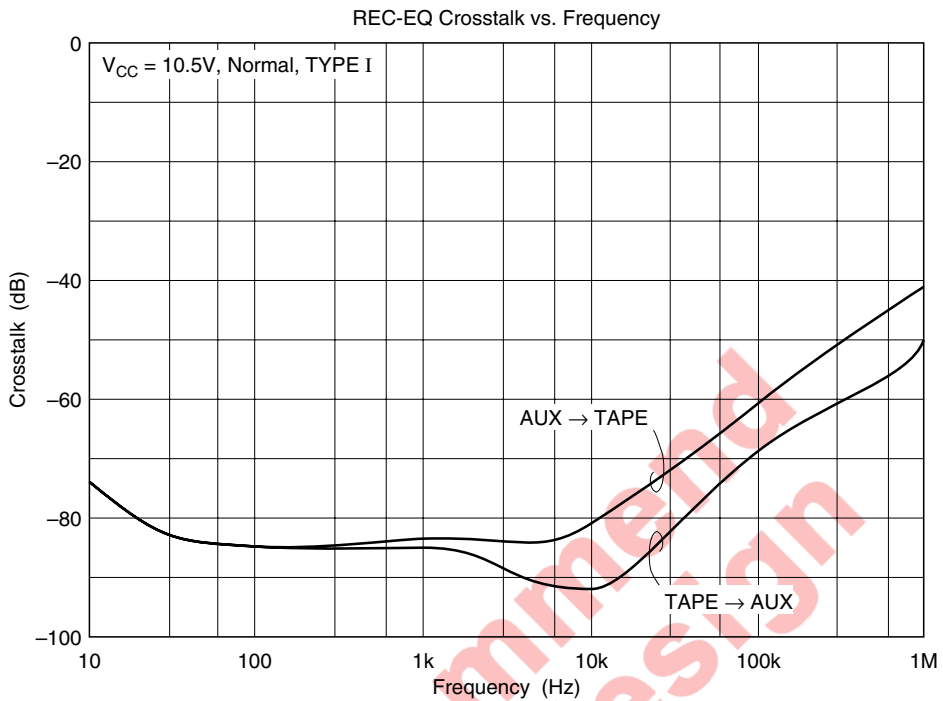


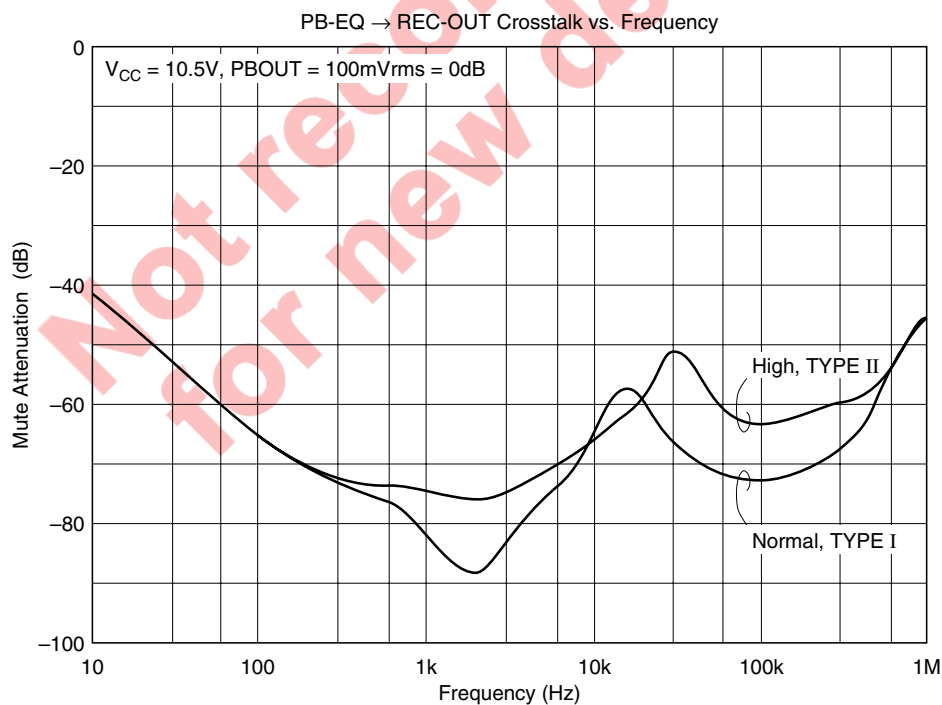
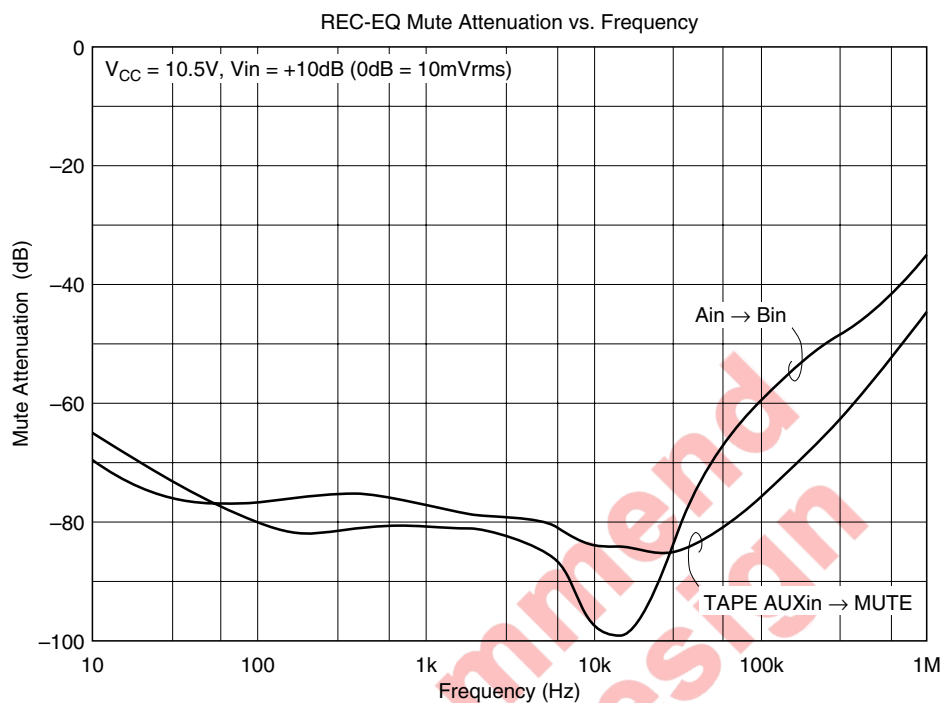


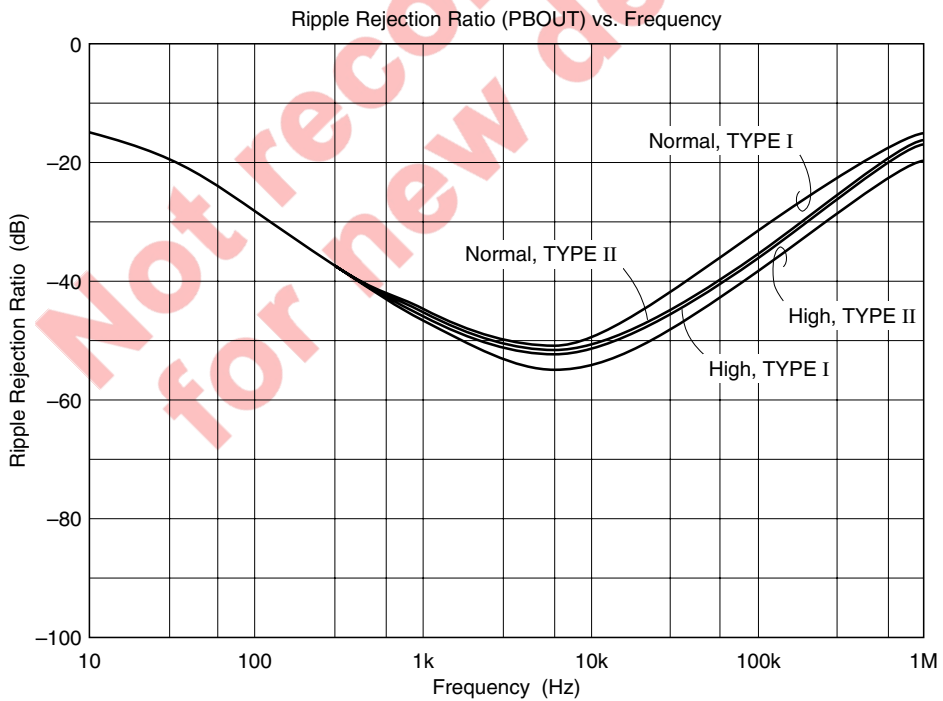
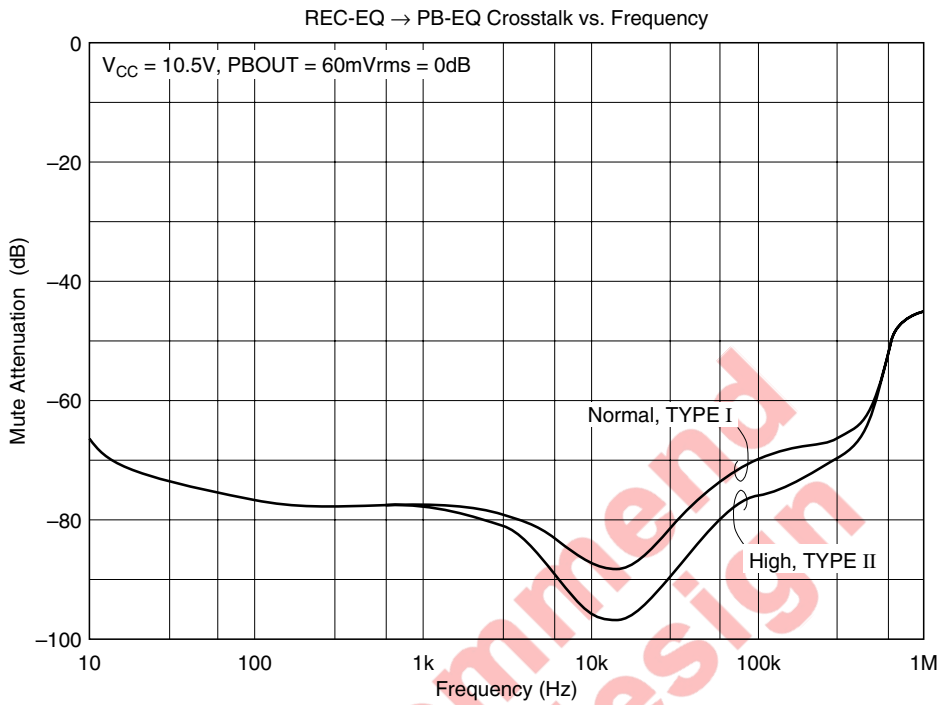


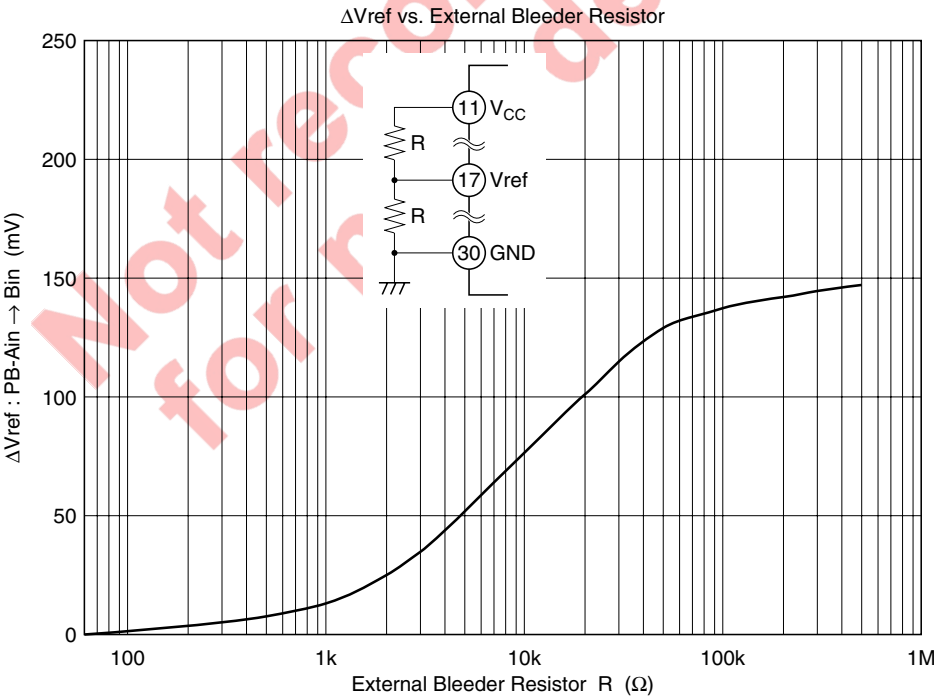
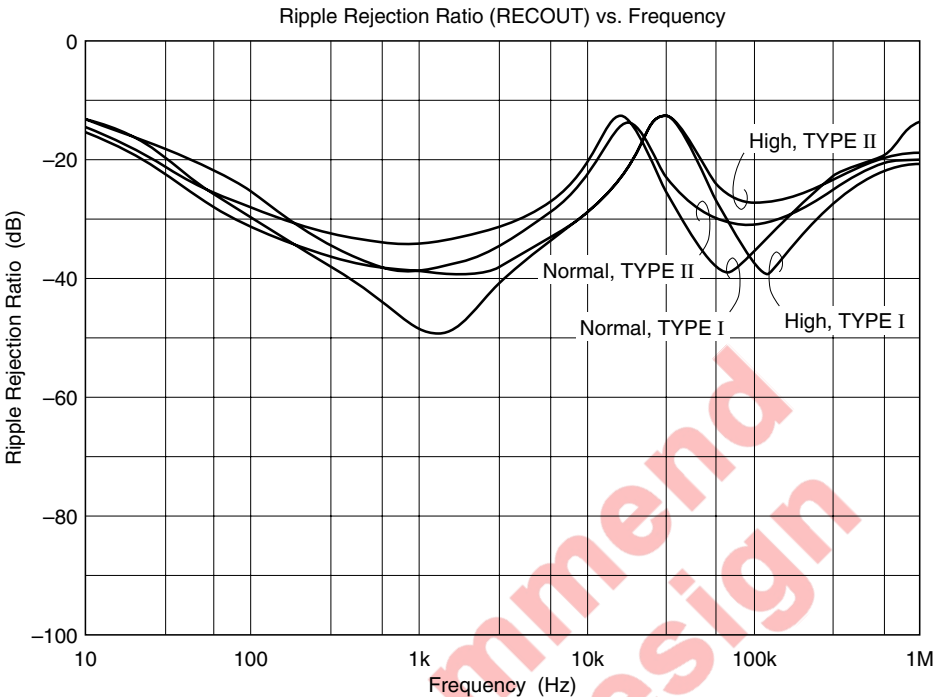


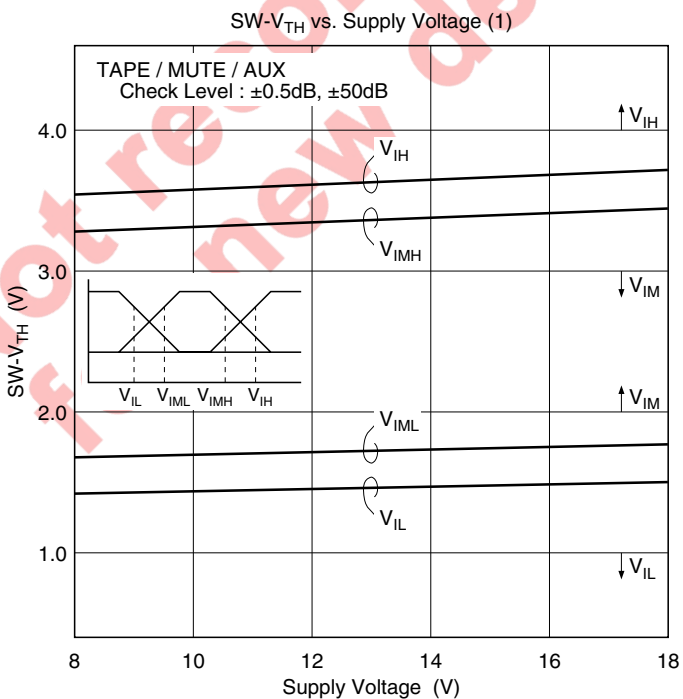
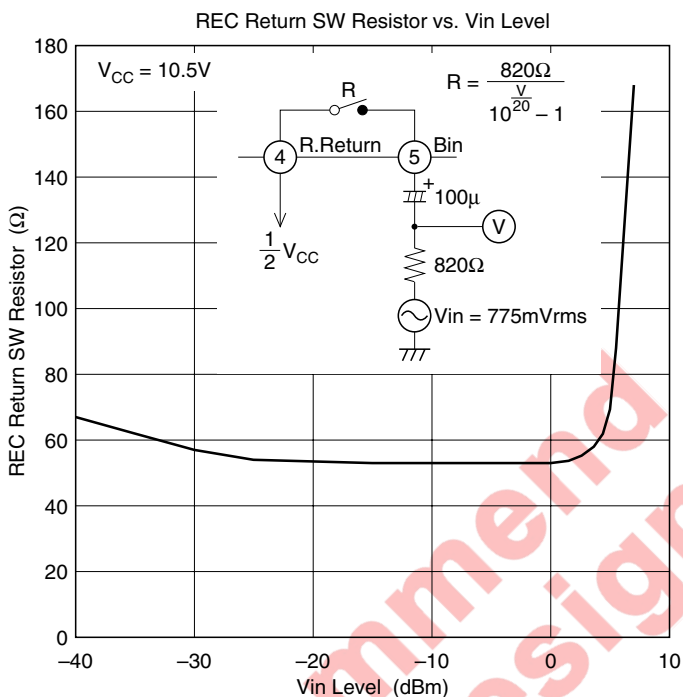


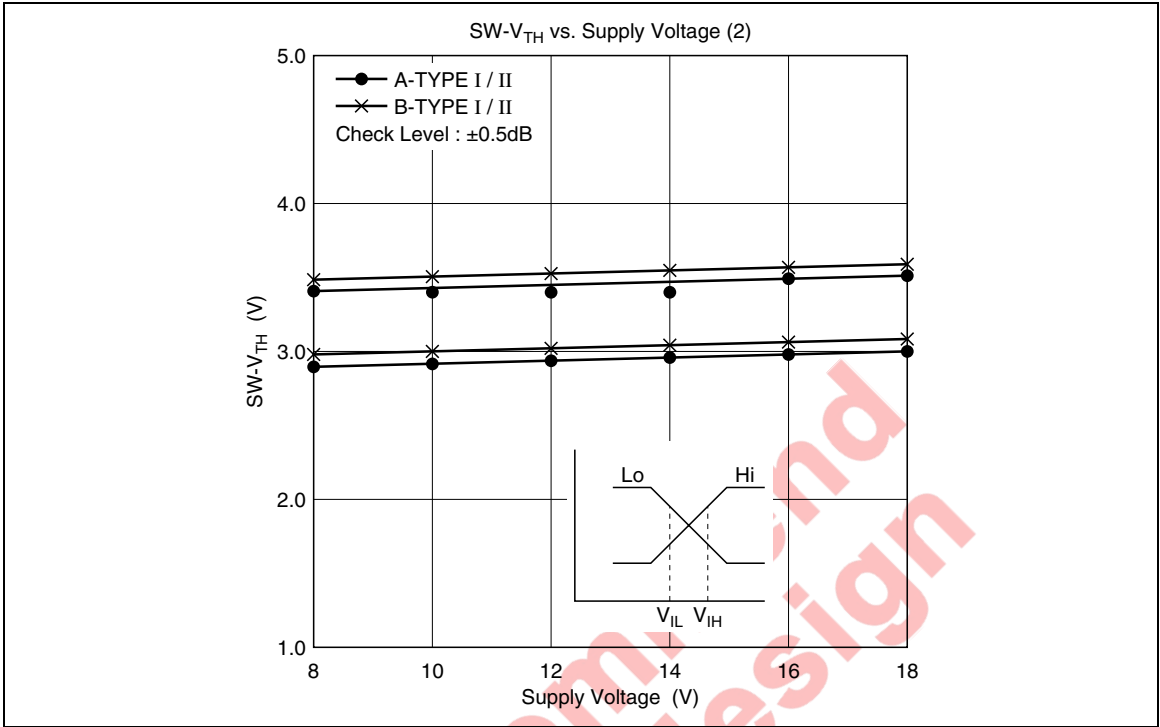






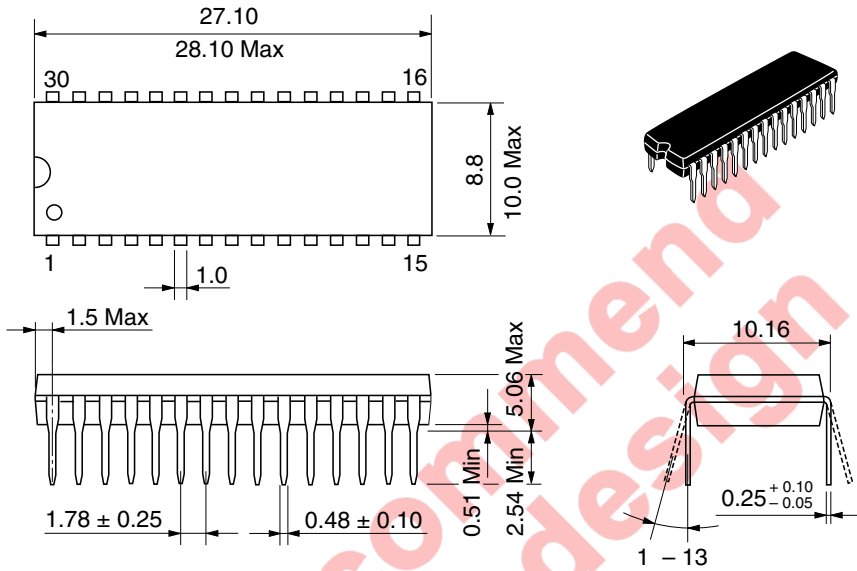






Package Dimensions

Unit: mm



Hitachi Code	DP-30S
JEDEC Code	—
EIAJ Code	SC-549-30
Weight	1.98 g

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